

INTERCONNECTS

SERIES 850, 851, 852, 853 • .050" GRID HEADERS AND SOCKETS • SINGLE AND DOUBLE ROW STRIPS

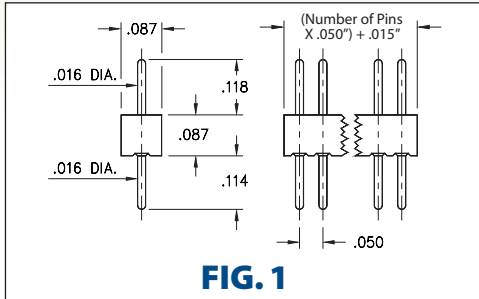


FIG. 1

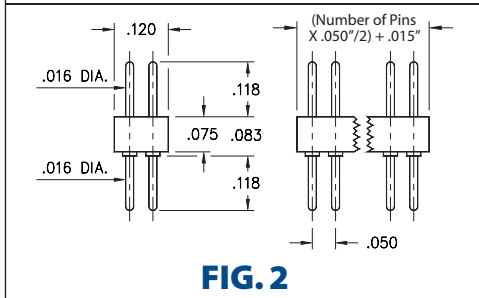


FIG. 2

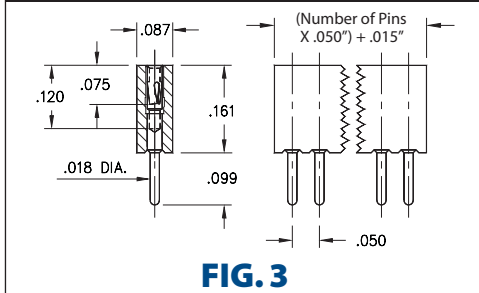


FIG. 3

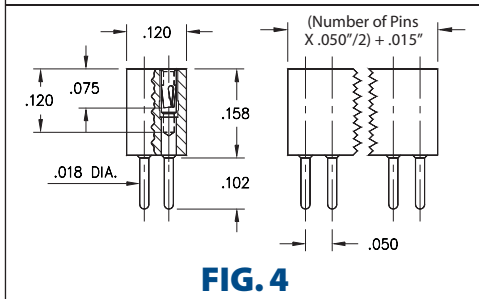


FIG. 4

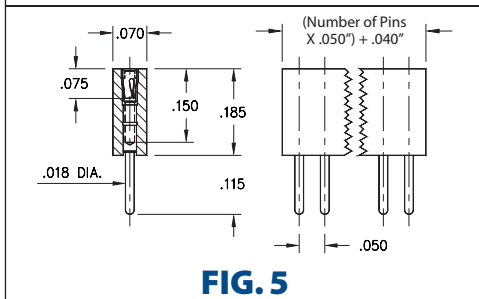
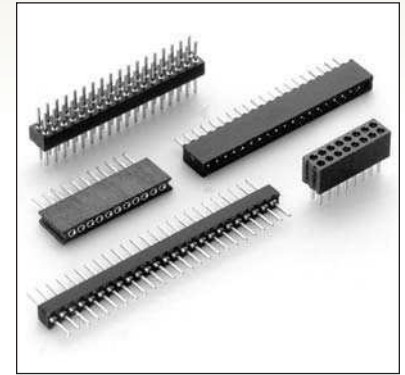


FIG. 5

- Series 850, 851, 852, 853 single and double row interconnects have .050" pin spacing and permit board stacking as low as .248"
- Pin headers have .016" dia. pins (MM #4006-0) See page 208 for details
- MM #0467 and MM #4890 receptacles use Hi-Rel, 3-finger BeCu #11 contact rated at 3 amps. (#11 contact accepts pin diameters from .015"-.020"). See pages 158 and 160 for details
- Insulators are high temperature thermoplastic, suitable for all soldering operations



ORDERING INFORMATION

FIG. 1	Series 850...001	Single Row .087" Profile Pin Header		
		850-XX-0	-10-001000	
	Specify number of pins		01-50	
FIG. 2	Series 852...001	Double Row .083" Profile Pin Header		
		852-XX-	-10-001000	
	Specify number of pins		002-100	
RoHS 2002/95/EC		XX=Plating Code See Below		<i>For Electrical, Mechanical & Environmental Data, See page 264</i>
SPECIFY PLATING CODE XX=		10 \diamond	90	40 \diamond
Pin Plating		10 μ " Au	200 μ " Sn/Pb	200 μ " Sn

FIG. 3	Series 851...001	Single Row .161" Profile Socket				
		851-XX-0	-10-001000			
	Specify number of pins		01-50			
FIG. 4	Series 853...001	Double Row .161" Profile Socket				
		853-XX-	-10-001000			
	Specify number of pins		002-100			
FIG. 5	Series 851...002	Single Row .185" Profile Socket				
		851-XX-0	-10-002000			
	Specify number of pins		01-77			
RoHS 2002/95/EC		XX=Plating Code See Below		<i>For Electrical, Mechanical & Environmental Data, See page 264</i>		
SPECIFY PLATING CODE XX=		91	93	99	41 \diamond	43 \diamond
Sleeve (Pin)		200 μ " Sn/Pb	200 μ " Sn/Pb	200 μ " Sn/Pb	200 μ " Sn	200 μ " Sn
Contact (Clip)		10 μ " Au	30 μ " Au	100 μ " Sn/Pb	10 μ " Au	30 μ " Au